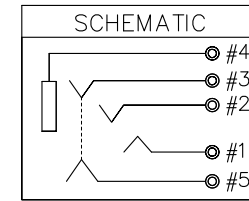
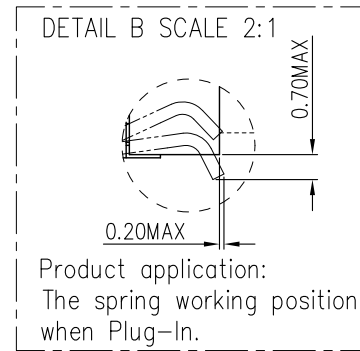
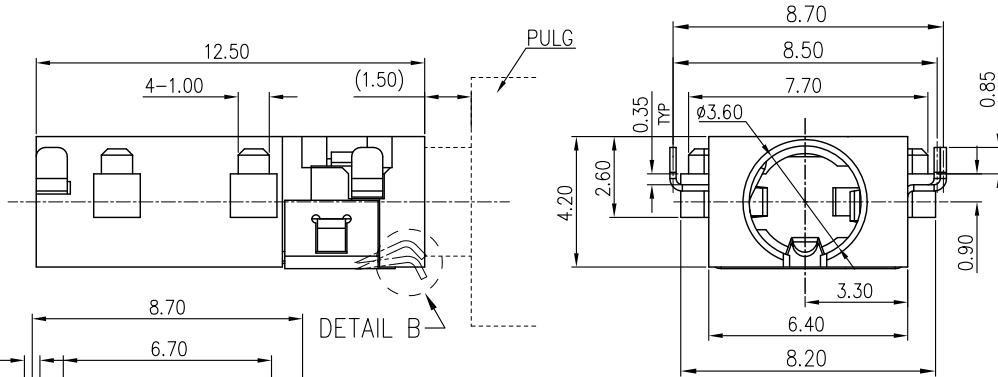
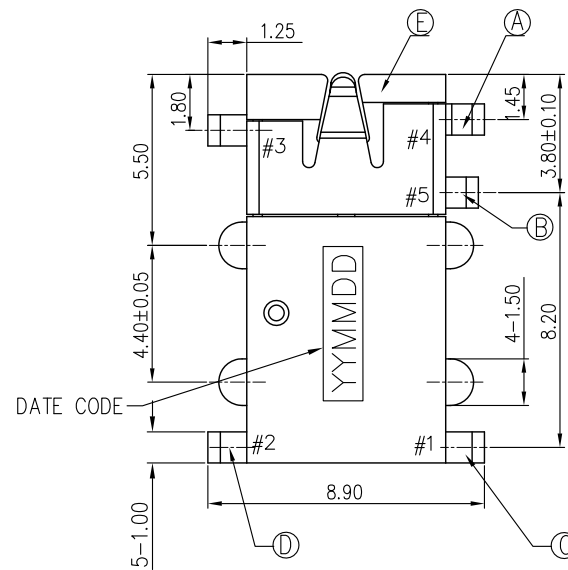
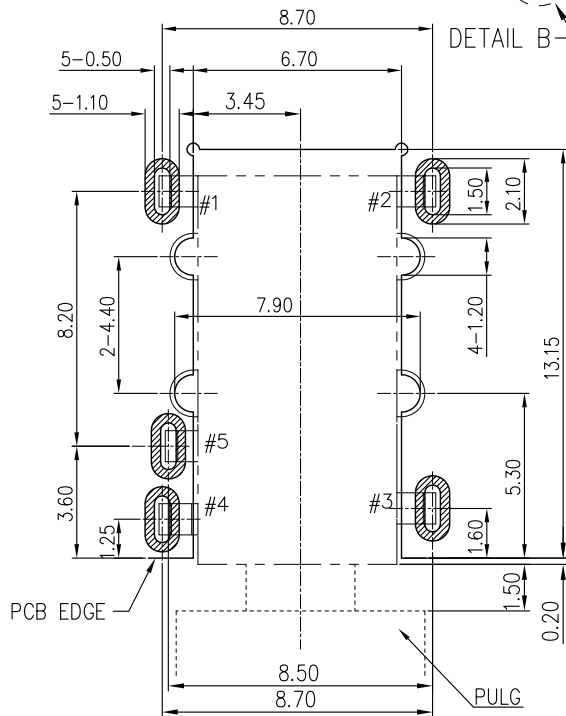


REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PRODUCT RELEASE	WEIQG	2012.03.26
B	ECN:C120193 UPDATE DRAWING	DAOWEN	2012.06.15

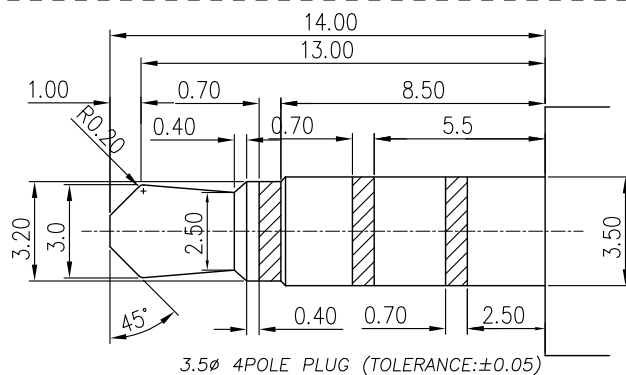
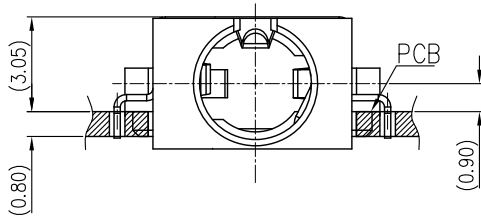


SPECIFICATIONS:

- ELECTRICAL CHARACTERISTICS:**
 - 1-1. RATING: 12V 1A
 - 1-2. CONTACT RESISTANCE: 30mΩ MAX.(INITIAL)
 - 1-3. DIELECTRIC WITHSTANDING VOLTAGE: 500V AC FOR ONE MINUTE.
 - 1-4. INSULATION RESISTANCE: 100MΩ MIN. MEASURED BY 500 VDC
- MECHANICAL CHARACTERISTICS:**
 - 2-1. INSERTION FORCE : 0.3~3.0 KGF
 - 2-2. WITHDRAWAL FORCE : 0.3~3.0 KGF
- LIFE TEST: 5,000 CYCLES MIN.**
- OTHER GENERAL SPEC. TO REFER "3.5ΦPHONE JACK SPEC".**
- TO CONFORM TO THE SINGATRON HSF SPEC.**
- HALOGEN FREE PRODUCT IDENTIFICATION MARK ON PRODUCT.**
- HALOGEN FREE PRODUCT IDENTIFICATION LABEL ON PACKAGING.**
- FOR REFLOW SOLDERING LEAD-FREE PROCESS.**
- PACKAGING: TAPE & REEL.**



RECOMMENDED PCB LAYOUT
TOP VIEW (TOLERANCE: ±0.05)



NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
E	BODY	1	THERMOPLASTIC HIGH TEMP	NATURE(WHITE)
D	RING SPRING A	1	COPPER ALLOY 0.2t	GOLD FLASH
C	TIP SPRING	1	COPPER ALLOY 0.2t	Gold Flash on contact area and Solder tail, all over Nickel Plated
B	RING SPRING B	2	COPPER ALLOY 0.2t	GOLD FLASH
A	EARTH	1	COPPER ALLOY 0.2t	GOLD FLASH

UNLESS OTHERWISE SPECIFIED TOLERANCES		Singatron Enterprise Co., Ltd. 信音企業股份有限公司	
DECIMALS: ANGLES:		TITLE: 3.5Φ PHONE JACK	
X : ±0.5	X : ±2°	DWN	DAOWEN 2012.09.12 PART NO. 2SJ2271-131111F
X.X : ±0.3	X.X : ±1°	CHKD	ZIZ 2012.09.12 SCALE 6:1 UNIT: mm
X.XX : ±0.2		APVD	LWD 2012.09.13 SIZE: A3 SHEET: 10F1 REV: B
CUSTOMER COPY			